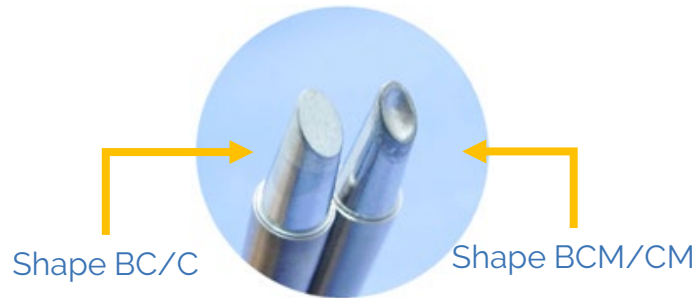
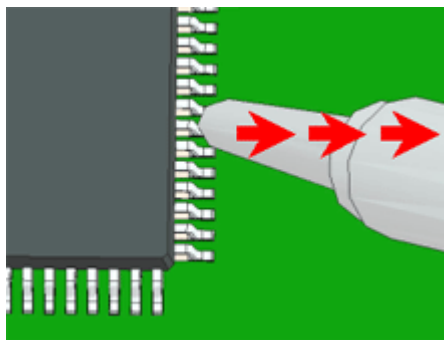
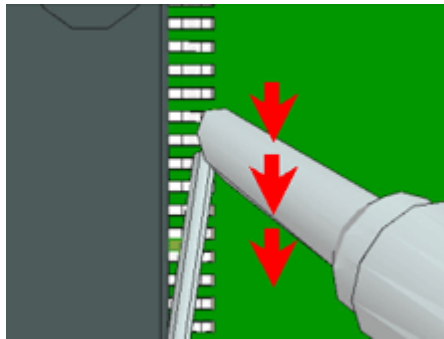


How to use Shape BCM/CM + Examples



The Shape BCM/CM tip differs from Shape BC/C by the addition of a hollow to its cut face, providing high solder retention capability. It is used for drag soldering and correction of bridging.

The surface tension of solder in the hollow section enables bridging to be corrected and prevents bridging from occurring when drag soldering.



NOTE: If solder amount of the bridge is large, Shape J, K and H are recommended.

Drag Soldering

Since the pulling force due to surface tension of this type is stronger than that of Shape BC, solder is not left in unnecessary areas during drag soldering.

1. Feed solder on a hollow section and drag the tip along slowly.
2. Applying flux to leads and land pads before soldering prevents solder bridge.

Correcting Bridging

When the tip is placed onto the bridge, solder that was left in the hollow section pulls solder from the bridge, removing it.

1. Clean the hollow section with a cleaning sponge, etc. A small amount of solder may be left in the hollow section to aid removal of bridge.
2. Put the tip on the bridge section and drag it slowly.